BGF100

Microphone Filter and ESD Protection

Small Signal Discretes



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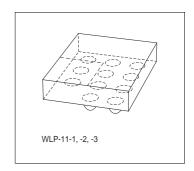
BGF100	
Revision	n History: 2006-10-17, V2.1
Previous	s Version: 2006-01-30
Page	Subjects (major changes since last revision)
All	Layout conformation



Microphone Filter and ESD Protection

Features

- · Differential Microphone filter
- Integrated ESD protection up to 15 kV
- Low input impedance
- · More than 30 dB stopband attenuation
- Ideal for GSM/UMTS
- Wafer Level Package with SnAgCu solder balls



Description

The BGF100 is a microphone filter with low pass characteristic offering a very high stop band attenuation up to 6 GHz. It also provides an ESD protection at the input pins up to 15 kV contact discharge. The wafer level package is a green leadfree package with a size of only 1.6 mm \times 2.1 mm and a total height of 0.65 mm.

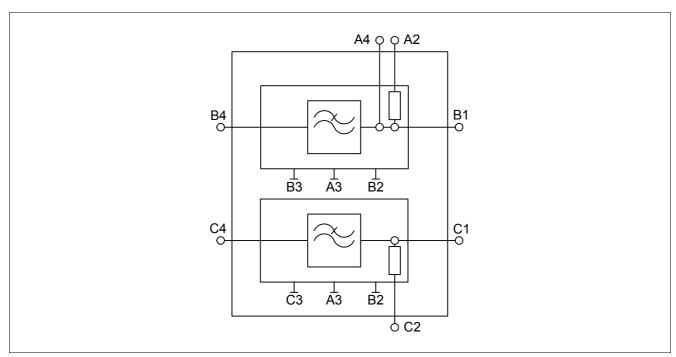


Figure 1 Blockdiagram

Туре	Package	Marking	Chip
BGF100	WLP-11-2	BGF100	N0700

Table 1 Maximum Ratings

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Voltage at pin A2 to GND	V_{A2}	0		4	V	
Voltage at all other pins to GND	V_{P}	-14		14	V	
Operating temperature range	T_{OP}	-40		+85	°C	



Table 1 Maximum Ratings (cont'd)

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Storage temperature range	T_{STG}	-65		+150	°C	
Input power at all pins	P_{IN}			1	mW	
Electrostatic Discharge According to IEC61	000-4-2					
Contact discharge at pins B4 to B3, C4 to C3	V_{E}	-15		15	kV	
Contact discharge between all other pins	V_1	-2		2	kV	

Table 2 Electrical Characteristics¹⁾

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Resistors R_1 , R_2	$R_{1,2}$	45	50	55	Ω	
Resistors R_3 , R_4	$R_{3,4}$	950	1000	1050	Ω	
Resistors R_5 , R_6	R _{5,6}	1980	2200	2420	Ω	
Resistor Matching R_3 , R_4	R_{M}	-1		+1	%	
Capacitances C_1 to C_6	C	800	1000	1350	pF	
Substrate leakage currents, Pin B4 to A3 or C4 to A3	I			100	nA	V = 3 V
Insertion loss ²⁾	IL	30			dB	f = 0.1 6 GHz
Pins B4 to B1 or C4 to C1						$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω

¹⁾ at $T_{\rm A}$ = 25 °C

²⁾ Insertion loss (see also **Figure 3**) strongly depends upon source and load impedance. For RF test purposes a 50 Ω environment is used.



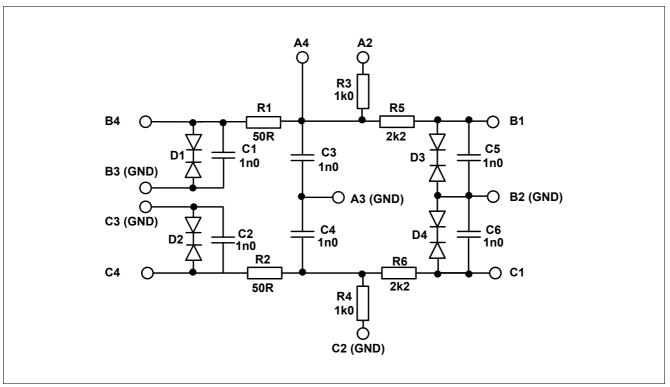


Figure 2 Schematic

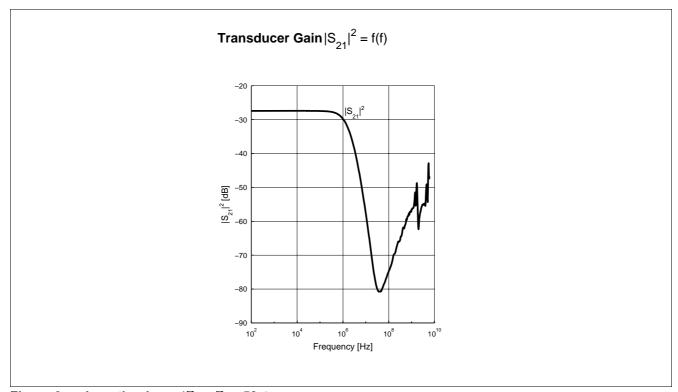


Figure 3 Insertion Loss ($Z_S = Z_L = 50 \Omega$)



Package Outlines

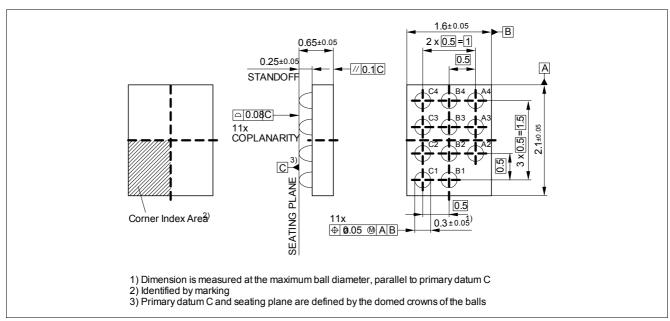


Figure 4 WLP-11-2

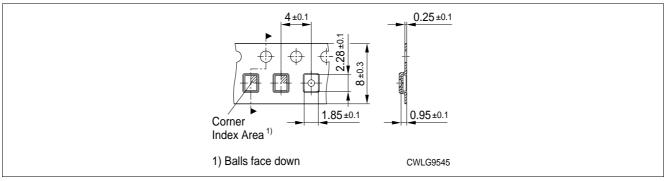


Figure 5 Tape for WLP-11-2

Dimensions in mm

You can find all of our packages, sorts of packing and others in our Infineon Internet Page "Products": http://www.infineon.com/products.